Abstract

This is a semiconductor device made by using a film carrier tape and method of making the same, wherein the package size is close to the chip size and connection portions for electrodes of a semiconductor chip are not exposed. Electroplating is performed in a state where connection leads 24, plating leads 26 and plating electrodes 28 are all conductive, the connection leads being are formed within a region to be filled with a molding material 36 and being connected to electrodes 42 of a semiconductor chip 40 and pad portions 22, the plating leads 26 being connected to the connection leads 24, and plating electrodes 28 being connected to the plating leads 26. The connection portions 29 are punched out into the region to be filled with the molding material, the connection leads 24 and the electrodes 42 are connected, and the molding material 36 is poured in. The end surfaces of the connection leads 24 that are exposed from the holes 32 are also covered by the molding material 36 so as not to be exposed.